

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 06/12/2022

Details for "TPS78433QDBVRQ1"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TPS78433QDBVRQ1	NIPDAU	Level-2-260C-1 YEAR	TI PHILIPPINES A/T	DBV   5	2.9x1.6x1.45	32.4

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Copper	7440-50-8	0.02851	96.663728	966637	0.088114	881
Precious Metals	Gold	7440-57-5	0.000161	0.545874	5459	0.000498	5
Precious Metals	Palladium	7440-05-3	0.000823	2.790398	27904	0.002544	25
Sub-Total			<b>0.029494</b>	<b>100</b>	<b>1000000</b>	<b>0.091155</b>	<b>912</b>
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	0.162797	74.999885	749999	0.503144	5031
Thermoplastics	Epoxy	85954-11-6	0.054266	25.000115	250001	0.167716	1677
Sub-Total			<b>0.217063</b>	<b>100</b>	<b>1000000</b>	<b>0.67086</b>	<b>6709</b>
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	19.439115	97.05	970500	60.07895	600789
Copper and Its Alloys	Iron	7439-89-6	0.52078	2.6	26000	1.609534	16095
Copper and Its Alloys	Phosphorus	7723-14-0	0.030045	0.15	1500	0.092858	929
Zinc and Its Alloys	Zinc	7440-66-6	0.04006	0.2	2000	0.12381	1238
Sub-Total			<b>20.03</b>	<b>100</b>	<b>1000000</b>	<b>61.905152</b>	<b>619052</b>
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.066584	95.12	951200	0.205786	2058
Precious Metals	Gold	7440-57-5	0.000546	0.78	7800	0.001687	17
Precious Metals	Palladium	7440-05-3	0.00287	4.1	41000	0.00887	89
Sub-Total			<b>0.07</b>	<b>100</b>	<b>1000000</b>	<b>0.216344</b>	<b>2163</b>
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	10.11672	87.999998	880000	31.266954	312670
Other Organic Materials	Chlorine	7782-50-5	0.000115	0.001	10	0.000355	4
Other Plastics and Rubber	Carbon Black	1333-86-4	0.034489	0.300002	3000	0.106592	1066
Thermoplastics	Epoxy	85954-11-6	1.344949	11.699	116990	4.156729	41567
Sub-Total			<b>11.496273</b>	<b>100</b>	<b>1000000</b>	<b>35.53063</b>	<b>355306</b>
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	0.51312	100	1000000	1.58586	15859
Sub-Total			<b>0.51312</b>	<b>100</b>	<b>1000000</b>	<b>1.58586</b>	<b>15859</b>
<b>Total</b>			<b>32.35595</b>			<b>100</b>	<b>1000000</b>

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

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Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.